

ABSTRACT

A chemical mechanical polishing (CMP) system and method for efficiently processing semiconductor wafers utilizes wafer transfer mechanisms that are strategically positioned in the system to efficiently transfer the wafers through the system. The efficient transfer of semiconductor wafers within the CMP system reduces congestion of wafers at various units of the system, which increases the throughput of the system. In addition to the efficient transfer of semiconductor wafers, the strategic positioning of the wafer transfer mechanisms minimizes the footprint of the CMP system.

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